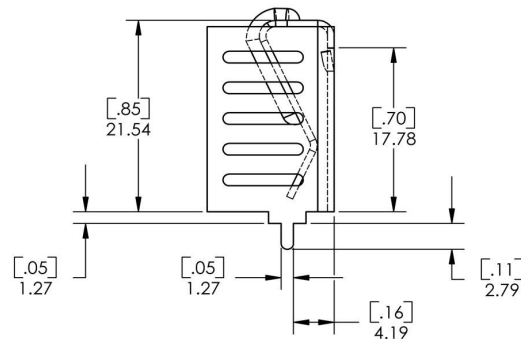
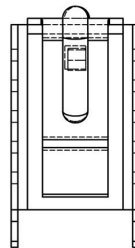
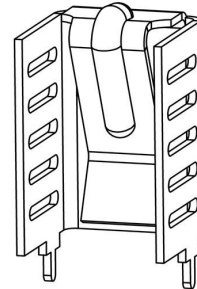
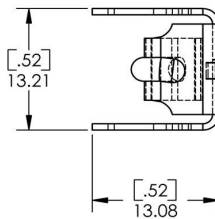
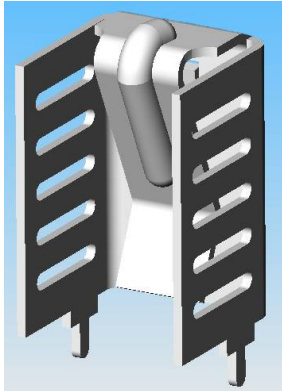


Board Level Heat Sinks



ThermaFlo

P/N: 833802T00000



PRODUCT SPECIFICATIONS

- Devices: TO-220
- Size: 13.1 x 13.2 x 24.0MM
- Material: Copper, 0.6MM Thick
- Type: Stamped
- Finish: Tin Plate
- IC Mounting: Integrated Spring
- PCB Mounting: Solderable Device Leads
- Package: Bulk

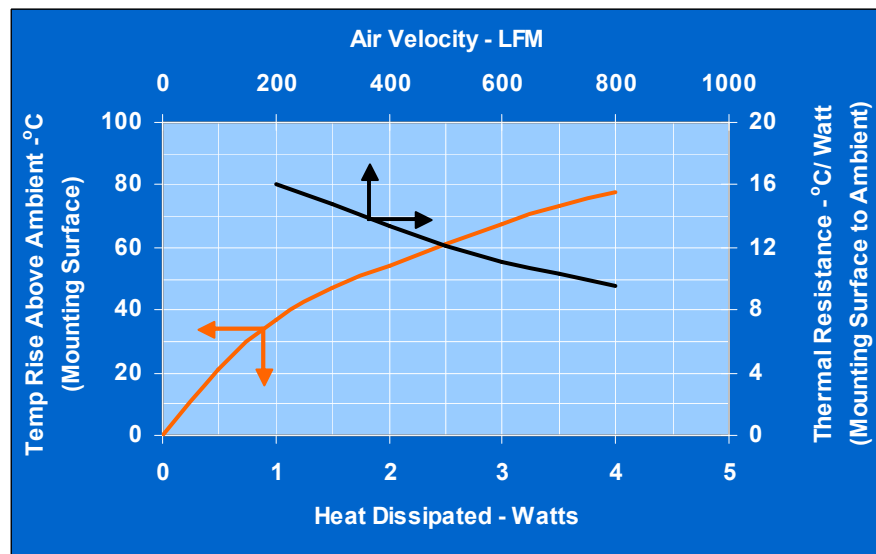
FEATURES & BENEFITS

- No Hardware Device Attachment
- Constant Spring Force Tension
- RoHS Compliant



CUSTOMIZED HEAT SINKS

- Specialized Tabs, Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220

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